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Total Number of Pages: 02

B.Tech.
PET5H002

5th Semester Regular Examination 2017-18

Digital VLSI Design

BRANCH: ECE, ETC

Time: 3 Hours

Max Marks: 100

Q.CODE: B452

Answer Question No.1 and 2 which are compulsory and any four from the rest.
The figures in the right hand margin indicate marks.

Q1¹⁰ Answer the following questions: *multiple type or dash fill up type* (2 x 10)

- a) What do you mean by fan out of a logic gate?
- The same amount of cooling required by a gate.
 - The physical distance between the output pins on device.
 - Number of other gates that can be connected to gate output.
 - Number of other gates that can be connected to gate input.
- b) Silicon dioxide layer is used
- To protect the surface.
 - It acts as barrier to dopant.
 - It acts as insulating substrate.
 - All of above.
- c) The threshold voltage is defined as
- The work function difference between gate and channel.
 - Gate voltage component to change surface potential.
 - Gate voltage to offset depletion region charge.
 - All of above.
- d) In n-channel mosfet transistor
- The source is at higher potential than drain.
 - The source is at lower potential than drain.
 - The source is at same potential than drain.
 - None of the above
- e) CMOS technology is better than bipolar technology because of,
- Its high noise margin.
 - Its low packing density.
 - Its low input impedance.
 - None of above.
- f) What do you mean by the rise time of a waveform,
- Time delay from when the input step changes by 50% to when the output step changes by 50%.
 - Time taken for the waveform to decrease from 90% to 10% of its value.
 - Time taken for the waveform to increase from 10% to 90% of its value.
 - Time taken for the waveform to increase from 50% to 100% of its value.
- g) nMos pass transistor can pass a _____ '0' signal.
- h) Elmore delay is used for measuring _____.
- i) Stuck at faults occur when a line is permanently stuck to _____.
- j) FPGA stands for _____.

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- Q2 Answer the following questions: Short answer type (2 x 10)**
- a) What do you understand by Local Oxidation of LOCOS.
 - b) What are the main parameters to be taken care of while designing any VLSI chip in general?
 - c) Draw $y=a'.b.c+c.d$ using CMOS design style.
 - d) What do you understand by Inversion Layer?
 - e) Draw the VTC of a CMOS inverter with proper labeling.
 - f) What do you understand by static and dynamic power.
 - g) What is the difference between combinational & sequential MOS circuits?
 - h) What is the need of testing a VLSI chip.
 - i) Which memory is fastest in operation?
 - j) What do you understand by a floating gate.
- Q3 a) Explain in detail VLSI design flow through Y-chart. (10)**
b) Describe the terms Regularity, Modularity and Locality. (5)
- Q4 a) Draw the fabrication steps for a CMOS device making process. (10)**
b) Write a note on Computer Aided Design Technology. (5)
- Q5 a) How does a MOS system will behave under external bias. Describe with the help of diagrams in regard to band diagram. (10)**
b) Considering the MOS structure made of a p-type silicon substrate, a SiO_2 layer, and a aluminum gate. The equilibrium Fermi potential of the doped silicon substrate is given as $q\Phi_{Fp} = 0.2$ eV. Using the electron affinity value for silicon as 0.95 eV and the work function for aluminum as 4.1 eV. Calculate the built-in potential difference across the MOS system. Assume that the MOS system contains no other charges in the oxide or on the silicon-oxide interface. (5)
- Q6 a) Derive the I-V equations for a nMOS for different regions of operation. (10)**
b) Write a note on scan-based techniques for VLSI testing. (5)
- Q7 a) Draw CMOS circuit diagram, stick diagram and layout diagram for a NOR2 gate with proper explanation. (10)**
b) Differentiate between inverters with enhancement type nMOS load and depletion type nMOS load. (5)
- Q8 a) Draw a 4:1 MUX using transmission gate logic. Compare it with its pass transistor counterpart. (10)**
b) Explain about DRAM with proper diagram. (5)
- Q9 a) Draw a neat and complete diagram for a 6 cell SRAM. Explain its operation in detail. (10)**
b) Draw a 2 input Ex-OR gate using pass transistor logic. (5)
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